# MSKSEMI















**ESD** 

TVS

TSS

MOV

GDT

**PLED** 

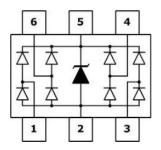
# Broduct data sheet





SOT-23-6

Pin Config uration



#### **Features**

Ultra low leakage: nA level

• Operating voltage: 5V

Low clamping voltage

• Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

Air discharge: ±15kV Contact discharge: ±10kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

- IEC61000-4-5 (Lightning) 5A (8/20 μs)

RoHS Compliant

# **Applications**

USB 2.0 power and data line

Set-top box and digital TV

Digital video interface (DVI)

Notebook Computers

SIM Ports

#### **Mechanical Characteristics**

• Package: SOT-23-6

• Lead Finish: Lead Free

UL Flammability Classification Rating 94V-0

• Quantity Per Reel:3,000pcs

Reel Size:7inch

# **Absolute Maximum Ratings**(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20µs)	Ррр	80	W	
ESD per IEC 61000-4-2 (Air)	- V <sub>ESD</sub>	±15	Kv	
ESD per IEC 61000-4-2 (Contact)	VESD	±10	rv	
Operating Temperature Range	TJ	-55 to +125	°C	
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	$^{\circ}$	

# **Electrical Characteristics**(TA=25°C unless otherwise specified)

P/N	V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	I <sub>⊤</sub> (mA)	V <sub>c</sub> @1A	(Max)	(@A)	I <sub>R</sub> µA (Max)	C (Pf) (Typ.)
USBLC6-4SC6-MS	5	6	1	12	16	5	1	0.6

#### **Characteristic Curves**

Fig1.  $8/20\mu$  s Pulse Waveform

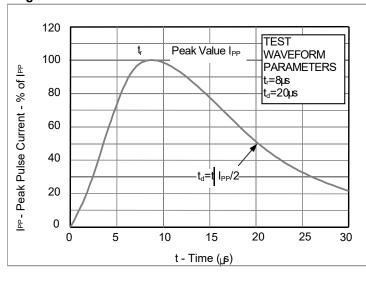


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

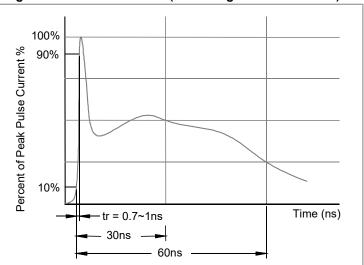
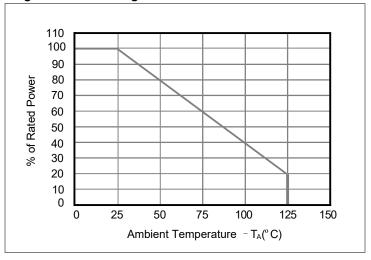
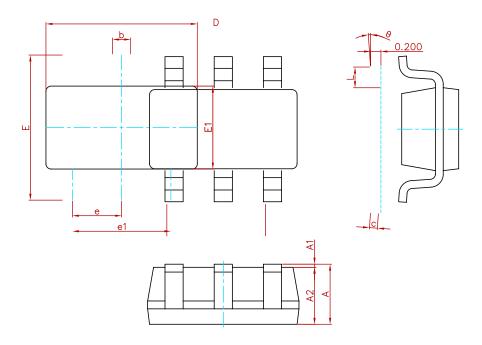


Fig3. Power Derating Curve



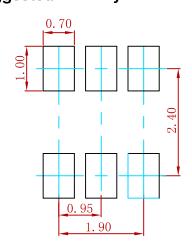


### **PACKAGE MECHANICAL DATA**



Symbol	Dimensions In	n Millimeters	Dimensions In Inches		
Syllibol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
Е	2.650	2.950	0.104	0.116	
е	0.950(	BSC)	0.037	(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

# **Suggested Pad Layout**



#### Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
USBLC6-4SC6-MS	SOT-23-6	3000



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